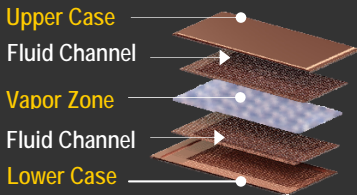


Celsia NanoSpreader¹ Vapor Coolers

NanoSpreader General Information



ENHANCED PERFORMANCE

Up to 30% better thermal performance than heat pipe solutions, with ten times the thermal conductivity and half the weight of solid copper

DESIGN VERSATILITY

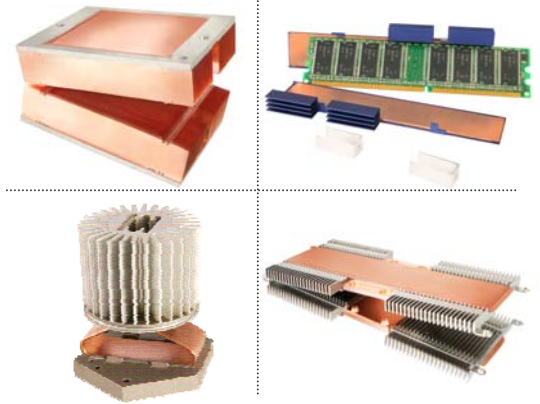
NanoSpreaders can be made as thin as 1.5mm with a very large surface area that is designed to come in direct contact with the heat source

IDEAL HEAT PIPE REPLACEMENT

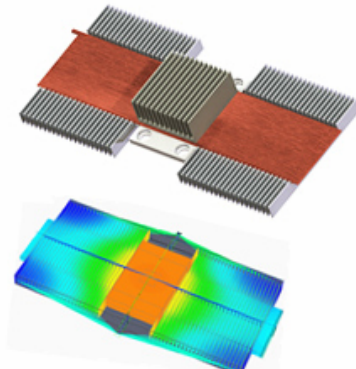
Most heat pipe applications can be replaced with a NanoSpreader solution for less cost, better performance, and in some cases both.

Unmatched Price / Performance Thermal Solutions

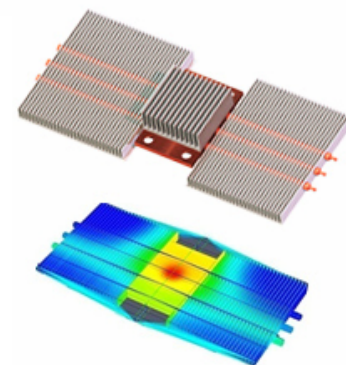
- NanoSpreaders are a patented, copper encased, two-phase vapor chamber with up to 30% better performance than heat pipes.
- Celsia can provide design, prototyping, and mass production of complete or partial thermal solutions.
- Application specialties include CPU & GPU, embedded processors, memory, and LED backlighting.



NanoSpreader™ Solution



Heat Pipe Solution



Heat Pipe Comparison

- One NanoSpreader can replace multiple heat pipes and provide a larger surface area for heat dissipation.
- In the example to the left, Celsia developed a solution that spread heat more evenly, resulting in 22% better thermal performance.
- NanoSpreaders are perfect for applications demanding better performance, lower weight, less mass, and an affordable price.

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¹ NanoSpreader is a registered trademark of Celsia Technologies